



Material Content Data Sheet



Sales Product Name	ESD8V0R1B-02LS E6327			Issued		30. January 2015		
MA#	MA000368753							
Package	PG-TSSLP-2-1			Weight*		0.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.23		2321	
	noble metal	gold	7440-57-5	0.001	0.90		8992	
	inorganic material	silicon	7440-21-3	0.017	10.98	12.11	109777	121090
leadframe	non noble metal	nickel	7440-02-0	0.036	24.19	24.19	241866	241866
wire	noble metal	gold	7440-57-5	0.003	1.84	1.84	18369	18369
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.03		273	
	organic material	carbon black	1333-86-4	0.001	0.54		5420	
	plastics	epoxy resin	-	0.011	7.32		73151	
	inorganic material	silicondioxide	60676-86-0	0.070	46.28	54.17	463016	541860
leadfinish	noble metal	gold	7440-57-5	0.004	2.74	2.74	27354	27354
plating	noble metal	silver	7440-22-4	0.007	4.95	4.95	49461	49461
*deviation	< 10%	Sum in total:			100.00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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